

October 1992 Revised March 1999

## 74VHC240

# Octal Buffer/Line Driver with 3-STATE Outputs

## **General Description**

The VHC240 is an advanced high speed CMOS octal bus buffer fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation. The VHC240 is an inverting 3-STATE buffer having two active-LOW output enables. This device is designed to drive buslines or buffer memory address registers.

An input protection circuit ensures that 0V to 7V can be applied to the input pins without regard to the supply voltage. This device can be used to interface 5V to 3V systems and two supply systems such as battery backup. This cir-

cuit prevents device destruction due to mismatched supply and input voltages.

#### **Features**

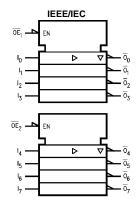
- High Speed:  $t_{PD} = 3.6$ ns (typ) at  $T_A = 25$ °C
- $\blacksquare$  Low power dissipation:  $I_{CC}$  = 4  $\mu A$  (max) @  $T_A$  = 25°C
- High noise immunity: V<sub>NIH</sub> = V<sub>NIL</sub> = 28% V<sub>CC</sub> (min)
- Power down protection is provided on all inputs
- Low noise:  $V_{OLP} = 0.9V$  (max)
- Pin and function compatible with 74HC240

## **Ordering Code:**

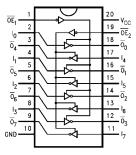
Order Number	Package Number	Package Description
74VHC240M	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74VHC240SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74VHC240MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74VHC240N	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Surface mount packages are also available on Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

## **Logic Symbol**



## **Connection Diagram**



## **Pin Descriptions**

Pin Names	Description					
$\overline{OE}_1, \overline{OE}_2$	3-STATE Output Enable Inputs					
I <sub>0</sub> -I <sub>7</sub>	Inputs					
$\overline{O}_0 - \overline{O}_7$	Outputs 3-STATE Outputs					

## **Truth Tables**

Inp	uts	Outputs
OE <sub>1</sub> I <sub>n</sub>		(Pins 12, 14, 16, 18)
L	L	Н
L	Н	L
н х		Z

Inp	uts	Outputs
OE <sub>1</sub>	I <sub>n</sub>	(Pins 3, 5, 7, 9)
L	L	Н
L	Н	L
н х		Z

- H = HIGH Voltage Level L = LOW Voltage Level X = Immaterial Z = High Impedance

#### **Absolute Maximum Ratings**(Note 1)

Supply Voltage (V<sub>CC</sub>) -0.5V to +7.0VDC Input Voltage ( $V_{IN}$ ) -0.5V to +7.0VDC Output Voltage (V<sub>OUT</sub>) -0.5 V to  $V_{CC} + 0.5 V$ Input Diode Current (I<sub>IK</sub>) -20 mA Output Diode Current (I<sub>OK</sub>) ±20 mA DC Output Current (I<sub>OUT</sub>) ±25 mA DC  $V_{CC}$ /GND Current ( $I_{CC}$ )  $\pm 75~\text{mA}$ Storage Temperature (T<sub>STG</sub>) -65°C to +150°C

Lead Temperature  $(T_L)$ 

(Soldering, 10 seconds) 260°C

# Recommended Operating Conditions (Note 2)

Operating Temperature ( $T_{OPR}$ ) Input Rise and Fall Time ( $t_r$ ,  $t_f$ )

$$\begin{split} V_{CC} = 3.3 V \pm 0.3 V & 0 \text{ ns/V} \sim 100 \text{ ns/V} \\ V_{CC} = 5.0 V \pm 0.5 V & 0 \text{ ns/V} \sim 20 \text{ ns/V} \end{split}$$

Note 1: Absolute Maximum Ratings are values beyond which the device may be damaged or have its useful life impaired. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables.Fairchild does not recommend operation outside databook specifications.

Note 2: Unused inputs must be held HIGH or LOW. They may not float.

#### **DC Electrical Characteristics**

Symbol	Parameter	V <sub>CC</sub>	T <sub>A</sub> = 25°C			$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		Units	Conditions	
		(V)	Min	Тур	Max	Min	Max	Units	Conditions	
V <sub>IH</sub>	HIGH Level	2.0	1.50			1.50		V		
	Input Voltage	3.0 - 5.5	0.7 V <sub>CC</sub>			0.7 V <sub>CC</sub>		v		
V <sub>IL</sub>	LOW Level	2.0			0.50		0.50	V		
	Input Voltage	3.0 – 5.5			$0.3  \mathrm{V_{CC}}$		$0.3~\mathrm{V}_\mathrm{CC}$	v		
V <sub>OH</sub>	HIGH Level	2.0	1.9	2.0		1.9			$V_{IN} = V_{IH}$	$I_{OH} = -50 \mu A$
	Output Voltage	3.0	2.9	3.0		2.9		V	or V <sub>IL</sub>	
		4.5	4.4	4.5		4.4				
		3.0	2.58			2.48		V		$I_{OH} = -4 \text{ mA}$
		4.5	3.94			3.80		V		$I_{OH} = -8 \text{ mA}$
V <sub>OL</sub>	LOW Level Output	2.0		0.0	0.1		0.1		$V_{IN} = V_{IH}$	$I_{OL} = 50  \mu A$
	Voltage	3.0		0.0	0.1		0.1	V	or V <sub>IL</sub>	
		4.5		0.0	0.1		0.1			
		3.0			0.36		0.44	V		$I_{OL} = 4 \text{ mA}$
		4.5			0.36		0.44	V		$I_{OL} = 8 \text{ mA}$
l <sub>OZ</sub>	3-STATE Output	5.5			±0.25		±2.5	μΑ	$V_{IN} = V_{IH}$	or V <sub>IL</sub>
	Off-State Current								$V_{OUT} = V_{CC}$ or GND	
I <sub>IN</sub>	Input Leakage Current	0 – 5.5			±0.1		±1.0	μΑ	V <sub>IN</sub> = 5.5\	or GND
Icc	Quiescent Supply Current	5.5			4.0		40.0	μΑ	$V_{IN} = V_{CC}$	or GND

## **Noise Characteristics**

Symbol	Parameter	v <sub>cc</sub>	T <sub>A</sub> =	25°C	Units	Conditions		
Cymbol	i didilotoi	(V)	Тур	Limits	Onito	Conditions		
V <sub>OLP</sub> (Note 3)	Quiet Output Maximum Dynamic V <sub>OL</sub>	5.0	0.6	0.9	V	C <sub>L</sub> = 50 pF		
V <sub>OLV</sub> (Note 3)	Quiet Output Minimum Dynamic V <sub>OL</sub>	5.0	-0.6	-0.9	V	C <sub>L</sub> = 50 pF		
V <sub>IHD</sub> (Note 3)	Minimum HIGH Level Dynamic Input Voltage	5.0		3.5	V	C <sub>L</sub> = 50 pF		
V <sub>ILD</sub> (Note 3)	Maximum LOW Level Dynamic Input Voltage	5.0		1.5	V	$C_L = 50 \text{ pF}$		

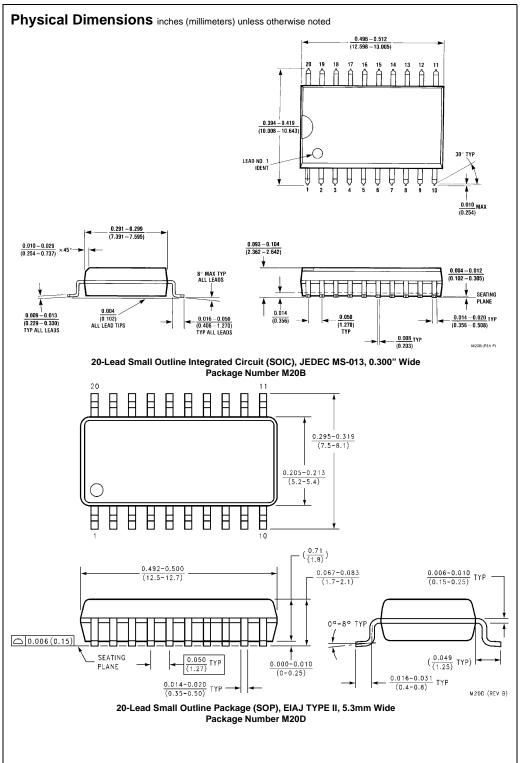
Note 3: Parameter guaranteed by design.

## **AC Electrical Characteristics**

Symbol	Parameter	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°	C to +85°C	Units	Conditions	
Oyillboi		(V)	Min	Тур	Max	Min	Max	Ullis	Conditions	
t <sub>PLH</sub>	Propagation	$3.3 \pm 0.3$		5.3	7.5	1.0	9.0	ns		C <sub>L</sub> = 15 pF
t <sub>PHL</sub>	Delay Time			7.8	11.0	1.0	12.5	115		C <sub>L</sub> = 50 pF
		$5.0 \pm 0.5$		3.6	5.5	1.0	6.5	ns	1	C <sub>L</sub> = 15 pF
				5.1	7.5	1.0	8.5	115		C <sub>L</sub> = 50 pF
t <sub>PZL</sub>	3-STATE	$3.3 \pm 0.3$		6.6	10.6	1.0	12.5	ns	$R_L = 1 k\Omega$	C <sub>L</sub> = 15 pF
t <sub>PZH</sub>	Output			9.1	14.1	1.0	16.0	115		$C_L = 50 pF$
	Enable Time	$5.0 \pm 0.5$		4.7	7.3	1.0	8.5	ns		$C_L = 15 pF$
				6.2	9.3	1.0	10.5	115		C <sub>L</sub> = 50 pF
t <sub>PLZ</sub>	3-STATE	$3.3 \pm 0.3$		10.3	14.0	1.0	16.0	ns	$R_L = 1 k\Omega$	$C_L = 50 pF$
$t_{PHZ}$	Output Disable Time	$5.0 \pm 0.5$	6.7		9.2	1.0	10.5	115		$C_L = 50 pF$
t <sub>OSLH</sub>	Output to	$3.3 \pm 0.3$			1.5		1.5	ns	(Note 4)	$C_{L} = 50 \text{ pF}$
t <sub>OSHL</sub>	Output Skew	$5.0 \pm 0.5$			1.0		1.0	ns		C <sub>L</sub> = 50 pF
C <sub>IN</sub>	Input Capacitance			4	10		10	pF	V <sub>CC</sub> = Oper	1
C <sub>OUT</sub>	Output Capacitance			6				pF	$V_{CC} = 5.0V$	
C <sub>PD</sub>	Power Dissipation			17				pF	(Note 5)	
	Capacitance									

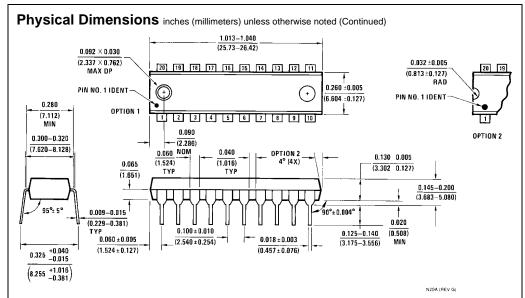
Note 4: Parameter guaranteed by design.  $t_{OSLH} = |t_{PLHmax} - t_{PLHmin}|; t_{OSHL} = |t_{PHLmax} - t_{PHLmin}|$ 

Note 5:  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC}$  (opr.) =  $C_{PD} * V_{CC} * f_{IN} + I_{CC}/8$  (per bit).



# Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 6.5±0.1 -0.20 7.72 6,4 4.4±0.1 -B-32 O.2 C B A PIN #1 IDENT. -LAND PATTERN RECOMMENDATION SEE DETAIL A -0.90+0.15 -0.10 0.09-0.20 -12.00° R0.09min GAGE PLANE DIMENSIONS ARE IN MILLIMETERS NOTES: <u>0.25</u>1 SEATING PLANE A. CONFORMS TO JEDEC REGISTRATION MD-153, VARIATION AC, REF NOTE 6, DATE 7/93. -0.6±0.1 -R0.09mln B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS. DETAIL A D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20



20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N20A

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